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**U.S. PATENT DOCUMENTS**

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
HP	3,464,855	9/02/069	Shaheen, et al.			
	5,549,808	8/27/96	Farooq, et al.			
	5,256,274	10/26/93	Poris			
	5,308,796	5/03/94	Feldman, et al.			
	5,198,389	3/30/93	van der Putten, et al.			
	5,240,879	8/31/93	De Bruin			
	3,385,773	5/28/68	John J. Frantzen			
	5,793,112	8/11/98	Hasegawa, et al.			
	6,251,771	6/26/01	Smith, et al.			
	6,207,552	3/27/01	Wang, et al.			
HP	6,110,648	8/29/00	Jang			

**FOREIGN PATENT DOCUMENTS**

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO

**OTHER DOCUMENTS** (Including Author, Title, Date, Pertinent Pages, Etc.)

HP			Electroless Plating for Low-Cost High-Leverage Wiring, IBM Technical Disclosure Bulletin, Vol. 32 No. 3A, August 1989

EXAMINER Uoaylan DATE CONSIDERED 8/12/04

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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PAGE 2 OF 2